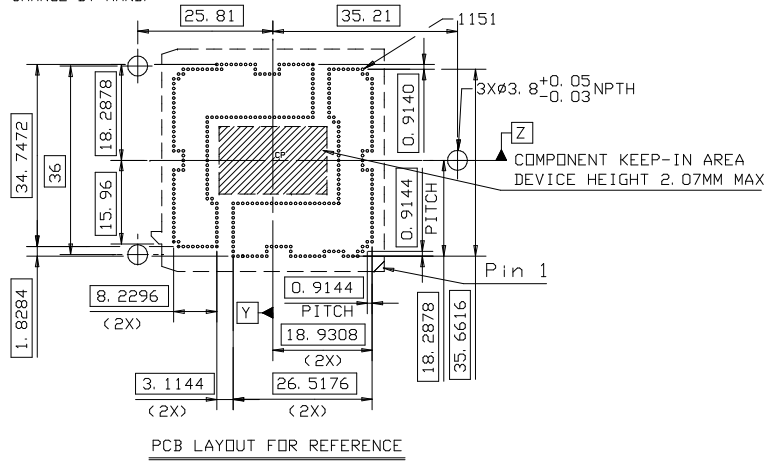
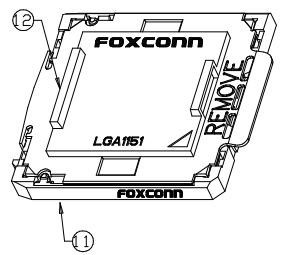


CAD GENERATED DRAWING, DO NOT CHANGE BY HAND.

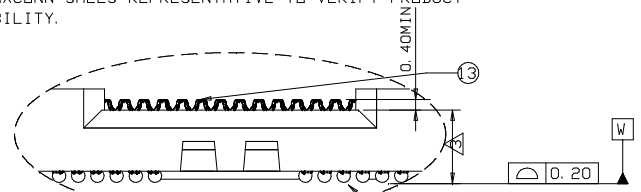
REV.	ECN. NO.	APPD.
A	BC-14-0014511	Dickie H

NOTES:

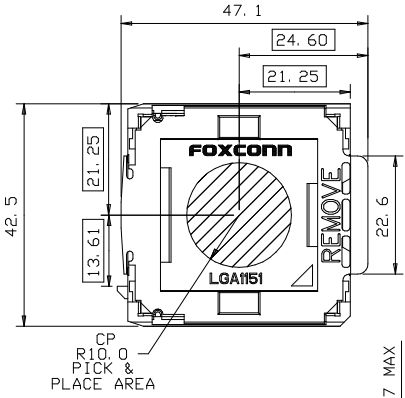
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- MATERIAL: SOCKET BODY LCP, UL94V-0, BLACK;
CONTACT Cu Ni ALLOY, 15u" MIN. Au PLATING OVER 50u" MIN.
N: UNDERPLATING ON CONTACT AREA;
PICK-UP CAP LCP, UL94V-0, BLACK;
SOLDERBALL LEAD FREE Sn/Ag/Cu BALL;
- THICKNESS OF SOCKET (FROM SEATING PLANE TO THE BOTTOM OF SOLDER BALLS): 3.4±0.20mm AFTER SOLDERING PROCESS
- DATE CODE & SOCKET NAME IS LOCATED APPROXIMATELY.
- FOXCONN LOGO IS LOCATED APPROXIMATELY.
- HARMFUL MATERIAL CONTROL PLEASE FOLLOWS DOC. NO. "EPI12"; (COMPLIANT TO ROHS)
- FOR GENERAL BOARD DESIGN, PLEASE REFER TO THE THERMAL AND MECHANICAL DESIGN GUIDELINES (TMDG) PROVIDED BY INTEL CORPORATION
- THE CONCENTRATIONS OF Br&Cl CAN SATISFY REQUIREMENTS OF HALOGEN-FREE IN DOCUMENT "EPI12"
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.



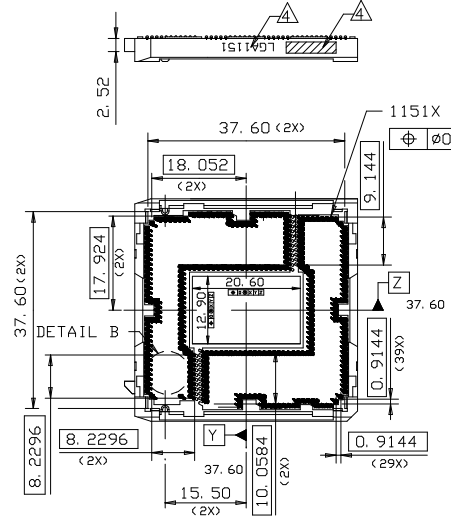
PCB LAYOUT FOR REFERENCE



DETAIL A
SCALE 4:1

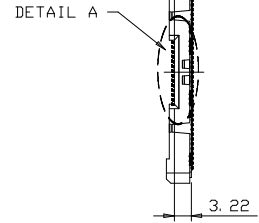


CP PICK-UP PLACE AREA

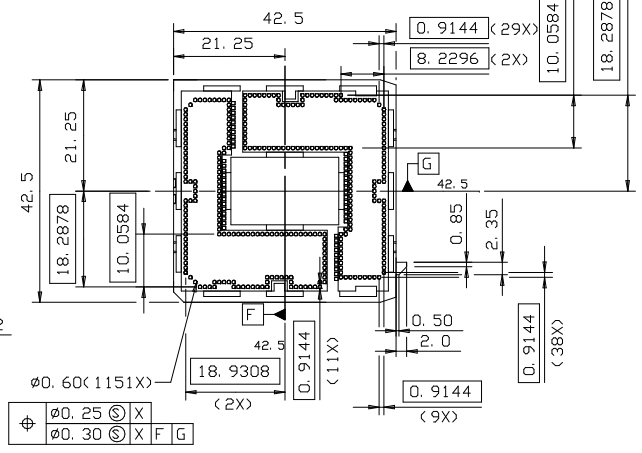


DETAIL B

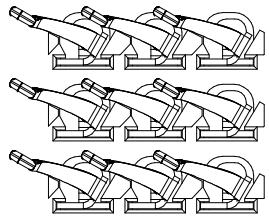
DETAIL B
SCALE 15:1



DETAIL A



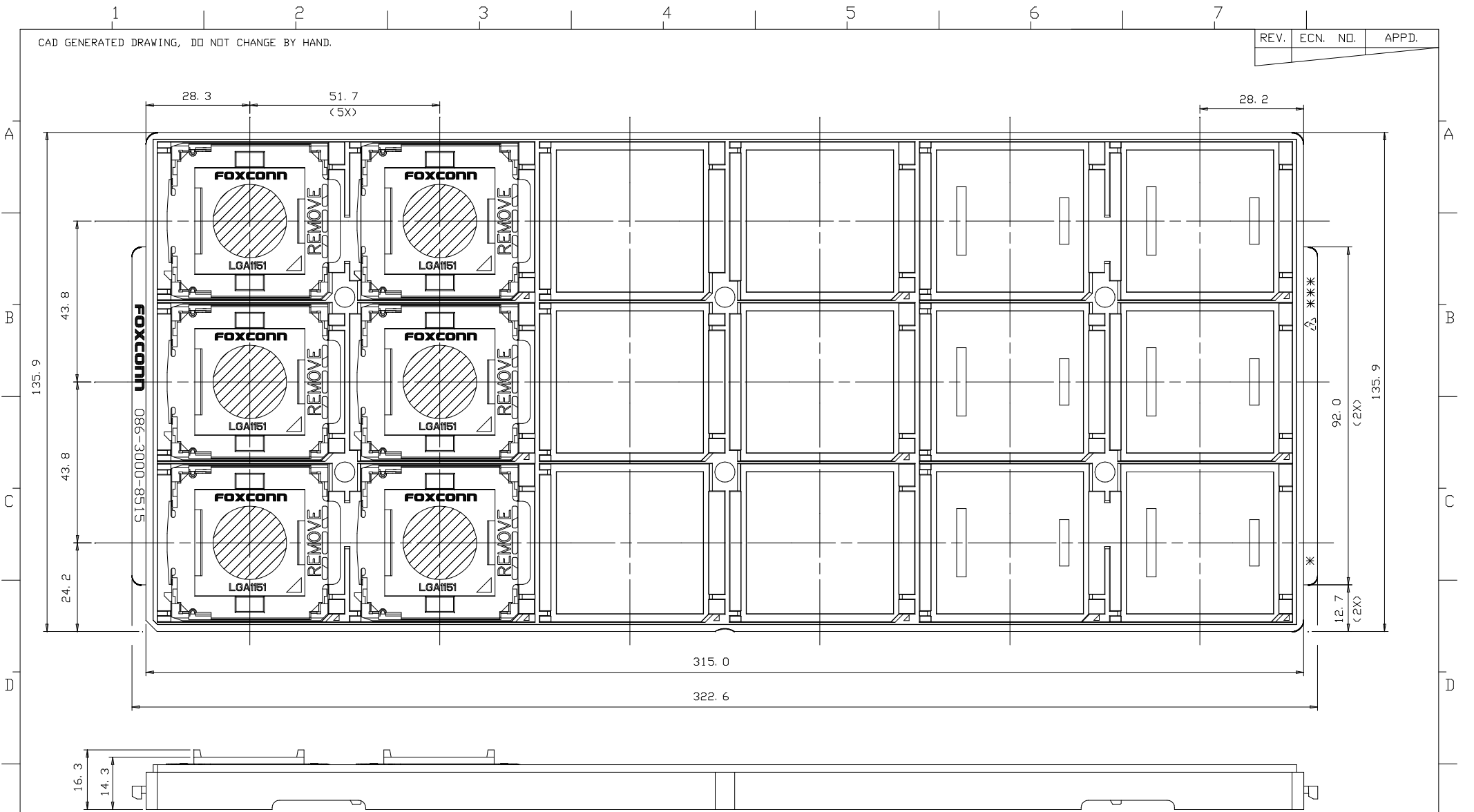
COMPONENT LIST (PE115127-4041-01H)		
ITEM	DESCRIPTION	Q' TY
①	SOCKET BODY	1
②	PICK & PLACE CAP	1
③	CONTACT	1151
④	SOLDER BALL	1151



X. ± 0.30	X. ° ± 1°	UNITS mm	NAME (INTENDED USE) LGA 1151 H4 SOCKET	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED. CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL						
. X ± 0.20	. X ° ±	MAT'L	PART NO. (INTENDED USE) PE115127-4041-01H							
. XX ± 0.10	. XX ° ±	FINISH	APPD: Nick Lin	TITLE: CUSTOMER DRAWING FOR LGA 1151 H4 SOCKET						
. XXX ±	. XXX ° ±		CHKD: Dickie Huang Mac Peng	DWG NO.: 351-0000-1294						
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			DR: Luke Qu 4/3/14	<table border="1"> <tr> <th>SCALE</th> <th>SHEET</th> <th>REV.</th> </tr> <tr> <td>2:1</td> <td>1/2</td> <td>A</td> </tr> </table>	SCALE	SHEET	REV.	2:1	1/2	A
SCALE	SHEET	REV.								
2:1	1/2	A								

CAD GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



X. ± 0.30	X. ° ± 1°	UNITS mm	NAME< INTENDED USE> LGA 1151 H4 SOCKET	Foxconn® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
. X ± 0.20	. X ° ±	MAT'L	PART NO. < INTENDED USE> PE115127-4041-01H	
. XX ± 0.10	. XX ° ±	FINISH	APPD: Nick Lin	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
. XXX ±	. XXX ° ±		Q' TY	CHKD: Dickie Huang Mac Peng
<small>THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.</small>			DR: Luke Qu 4/3/14	DWG NO. : 351-0000-1294